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A. Cont.

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: B. Beaman et al.

Date: February 13, 2001

Serial Number: 09/088,394

Group Art Unit: 2858

Filed: June 1, 1998

Examiner: V. Nguyen

For: HIGH DENSITY INTEGRATED CIRCUIT APPARATUS, Docket No.: YO993-028AB  
TEST PROBE AND METHODS OF USE THEREOFAssistant Commissioner for Patents  
Washington, D.C. 20231

## CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this Amendment (4 pages) and Petition and Fee for Extension of Time (1 page) are being facsimile transmitted under Rule 37 CFR 1.61(d) to the U.S. Patent and Trademark Office to (703) 305-1431 on February 13, 2001.

  
Dr. Daniel P. Morris, Esq.  
Reg. No. 32,053

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FEB 13 2001

TECHNOLOGY CENTER 2800

Sir:

AMENDMENT

In response to the Office Action dated October 13, 2000, please consider the following:

IN THE SPECIFICATION

At page 6, at the end thereof add Figure 17 shows the assembly of Figure 2 held by arms 200.

C Figure 18 schematically shows an apparatus for moving the probe structures of the present invention towards and away from an electronic device.

At page 17, before the last paragraph add Figure 17 shows the assembly of Figure 2 held

by arms 200. The IC wafer 50 is disposed on a base 202. The Arm 200 is movably mounted to

S.N. 09/088,394

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